

MOSFET Silicon N-Channel MOS

1. Applications

Synchronous rectification in SMPS,
Hard switching and High speed circuit
DC/DC in telecoms and industrial

2. Features

Low drain-source on-resistance:
 $R_{DS(on)}$ TOLL = 1.6m Ω (typ.)
 $R_{DS(on)}$ TO247 = 2.1m Ω (typ.)
High speed power switching
Enhanced body diode dv/dt capability
Enhanced avalanche ruggedness

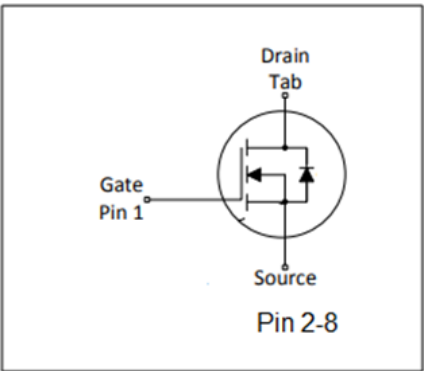
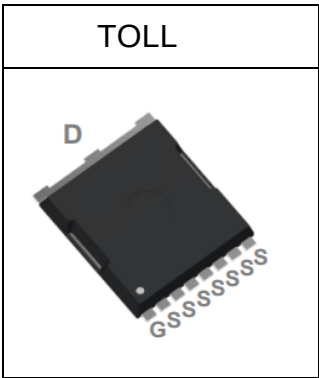
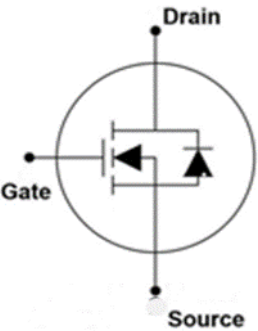
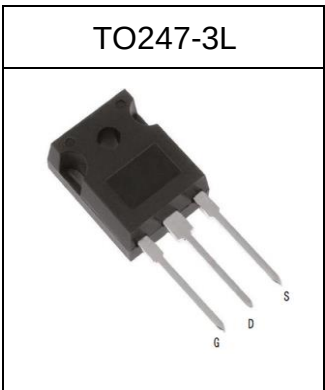


Table 1 Key Performance Parameters

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	100	V
$R_{DS(on),max}$ TOLL	2.0	m Ω
$R_{DS(on),max}$ TO247	2.5	m Ω
$Q_{g,typ}$	213	nC
$I_{D,pulse}$	1000	A

3. Packaging and Internal Circuit

Part Name	Package	Marking
AUR020N10	TOLL-8L	AUR020N10
AUW025N10	TO247-3L	AUW025N10



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1 Maximum ratings

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current ¹⁾	I_D		-	305	A	$T_C = 25^\circ\text{C}$
Pulsed drain current ²⁾	$I_{D,pulse}$	-	-	1000	A	$T_C = 25^\circ\text{C}$
Avalanche energy, single pulse	E_{AS}	-	-	1176	mJ	$T_C = 25^\circ\text{C}$, $V_{DD} = 50\text{V}$, $I_{av} = 68.6\text{A}$, $L = 0.5\text{mH}$, $R_G = 25\Omega$
Avalanche current, single pulse	I_{AR}	-	-	68.6	A	$T_C = 25^\circ\text{C}$, $V_{DD} = 50\text{V}$, $L = 0.5\text{mH}$, $R_G = 25\Omega$
Gate source voltage (static)	V_{GS}	-20	-	20	V	static;
Power dissipation	P_{tot}	-	-	375	W	$T_C = 25^\circ\text{C}$
Storage temperature	T_{stg}	-55	-	150	$^\circ\text{C}$	
Operating junction temperature	T_j	-55	-	150	$^\circ\text{C}$	
Soldering Temperature Distance of 1.6mm from case for 10s	T_L			260	$^\circ\text{C}$	

¹⁾ Limited by $T_{j,max}$. Maximum Duty Cycle $D = 0.50$

²⁾ Pulse width t_p limited by $T_{j,max}$

³⁾ Identical low side and high side switch with identical R_G

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2 Thermal characteristics

Table Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	0.33	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	48	°C/W	device on PCB, minimal footprint

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3 Electrical characteristics

at $T_j=25^{\circ}\text{C}$, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	100	-	-	V	$V_{GS}=0V, I_D=250\mu A$
Gate threshold voltage	$V_{(GS)th}$	2.5	3.1	4.5	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Zero gate voltage drain current	I_{DSS}	-	-	1	μA	$V_{DS}=100V, V_{GS}=0V, T_j=25^{\circ}\text{C}$
Gate-source leakage current	I_{GSS}	-	-	± 100	nA	$V_{GS}=\pm 20V, V_{DS}=0V$
Drain-source on-state resistance(TOLL)	$R_{DS(on)}$	-	1.6	2.0	m Ω	$V_{GS}=10V, I_D=20A, T_j=25^{\circ}\text{C}$
Drain-source on-state resistance(TO247)	$R_{DS(on)}$	-	2.1	2.5	m Ω	$V_{GS}=10V, I_D=20A, T_j=25^{\circ}\text{C}$
Gate resistance (Intrinsic)	R_G	-	1.6	-	Ω	$f=1\text{MHz}$, open drain
Transconductance	G_{fs}	-	138.4	-	S	$V_{DS}=5V, I_D=50A$

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	14994	-	pF	$V_{GS}=0V, V_{DS}=35V, f=1\text{MHz}$
Output capacitance	C_{oss}	-	1577	-	pF	$V_{GS}=0V, V_{DS}=35V, f=1\text{MHz}$
Reverse transfer capacitance	C_{rss}	-	477	-	pF	$V_{GS}=0V, V_{DS}=35V, f=1\text{MHz}$
Turn-on delay time	$t_{d(on)}$	-	35.5	-	ns	$V_{DD}=50V, V_{GS}=10V, I_D=20A, R_G=3\Omega$
Rise time	t_r	-	57.2	-	ns	$V_{DD}=50V, V_{GS}=10V, I_D=20A, R_G=3\Omega$
Turn-off delay time	$t_{d(off)}$	-	112	-	ns	$V_{DD}=50V, V_{GS}=10V, I_D=20A, R_G=3\Omega$
Fall time	t_f	-	62	-	ns	$V_{DD}=50V, V_{GS}=10V, I_D=20A, R_G=3\Omega$

Table 6 Gate charge characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	60.6	-	nC	$V_{DD}=50V, I_D=20A, V_{GS}=0 \text{ to } 10V$
Gate to drain charge	Q_{gd}	-	50.7	-	nC	$V_{DD}=50V, I_D=20A, V_{GS}=0 \text{ to } 10V$
Gate charge total	Q_g	-	213	-	nC	$V_{DD}=50V, I_D=20A, V_{GS}=0 \text{ to } 10V$
Gate plateau voltage	$V_{plateau}$	-	4.72	-	V	$V_{DD}=50V, I_D=20A, V_{GS}=0 \text{ to } 10V$

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Table 7 Reverse diode characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	V_{SD}	-	0.67	1.2	V	$V_{GS}=0V, I_F=1A, T_j=25^{\circ}C$
Reverse recovery time	t_{rr}	-	84.44	-	ns	$V_R=50V, I_F=20A, di_F/dt=100A/\mu s$
Reverse recovery charge	Q_{rr}	-	236	-	nC	$V_R=50V, I_F=20A, di_F/dt=100A/\mu s$
Peak reverse recovery current	I_{rrm}	-	4.31	-	A	$V_R=50V, I_F=20A, di_F/dt=100A/\mu s$

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4 Electrical characteristics diagram

Diagram 1: Typ. Output characteristics

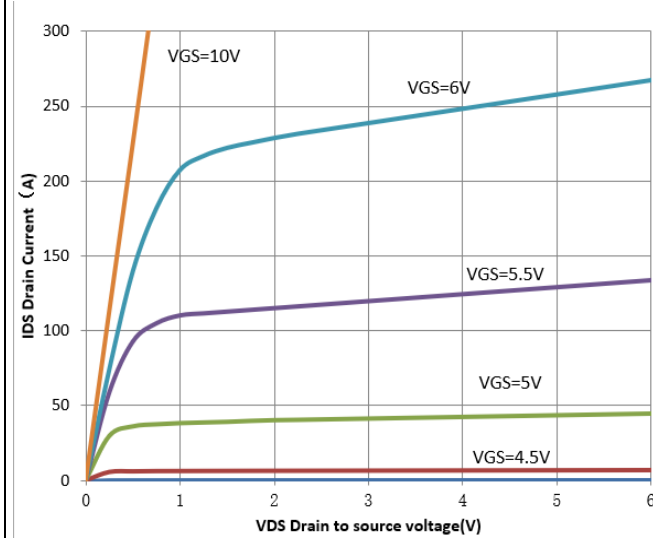

 $I_D = f(V_{DS}); T_J = 25^\circ\text{C}; \text{parameter: } V_{GS}$

Diagram 2: Typ. transfer characteristics

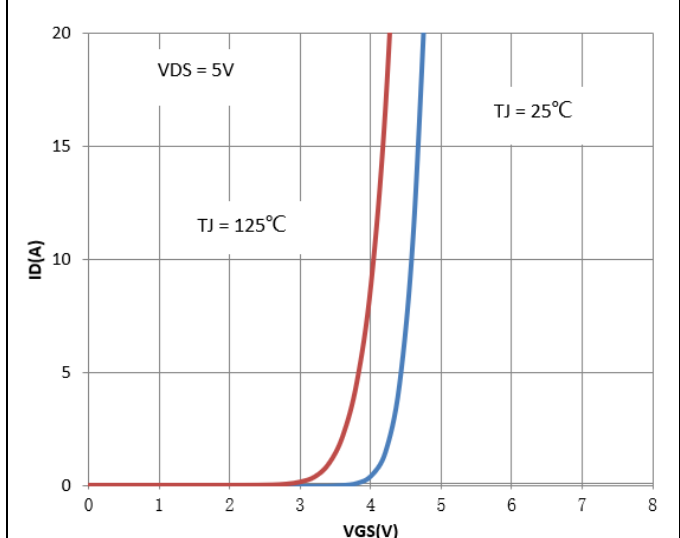

 $I_D = f(V_{GS}); V_{DS} = 5\text{V}; \text{parameter: } T_J$

Diagram 3: Typ. On-Resistance vs. ID (TOLL)

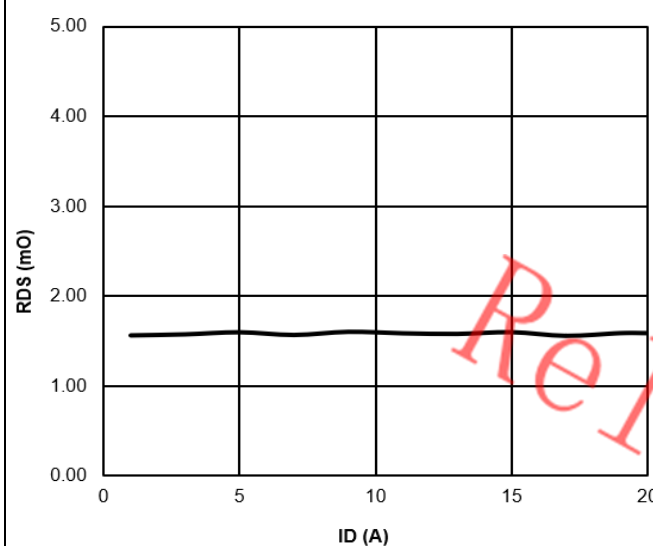

 $R_{DS(on)} = f(I_D); T_J = 25^\circ\text{C}; \text{parameter: } V_{GS} = 10\text{V (TOLL)}$

Diagram 4: Typ. Rdson – Junction Temperature

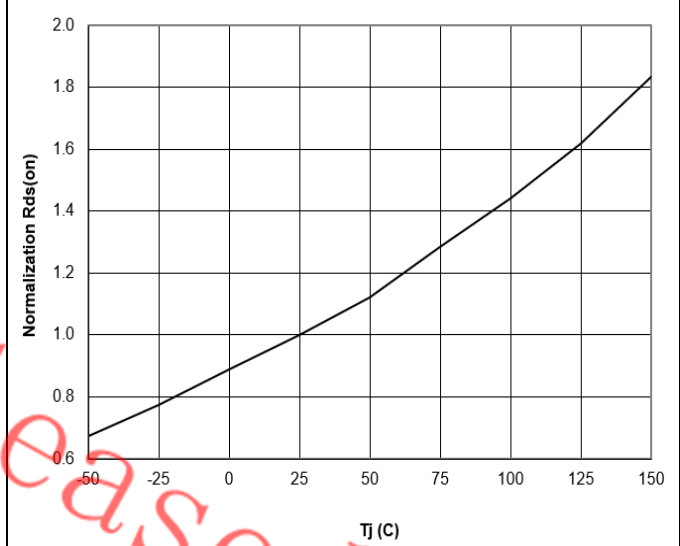

 $(R_{ds(on)} = f(T_J); V_{GS} = 10\text{V}; I_D = 20\text{A})$

Diagram 5: Typ. Body-Diode Characteristics

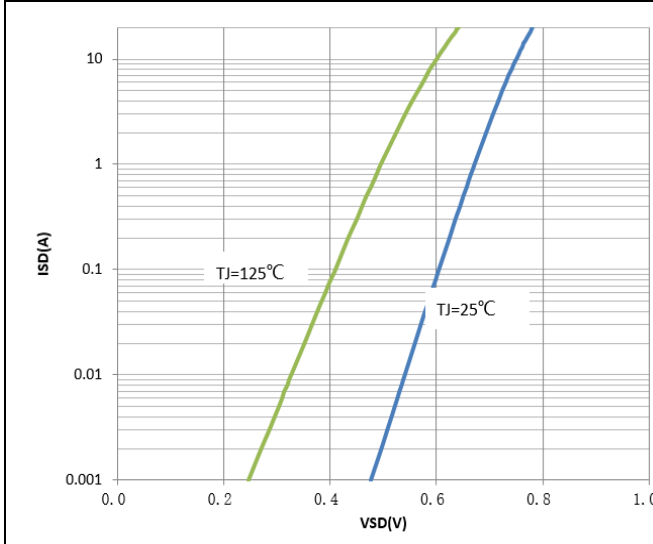

 $I_F = f(V_{DS}); \text{parameter: } T_J$

Diagram 6: Typ. Capacitance vs. Vds

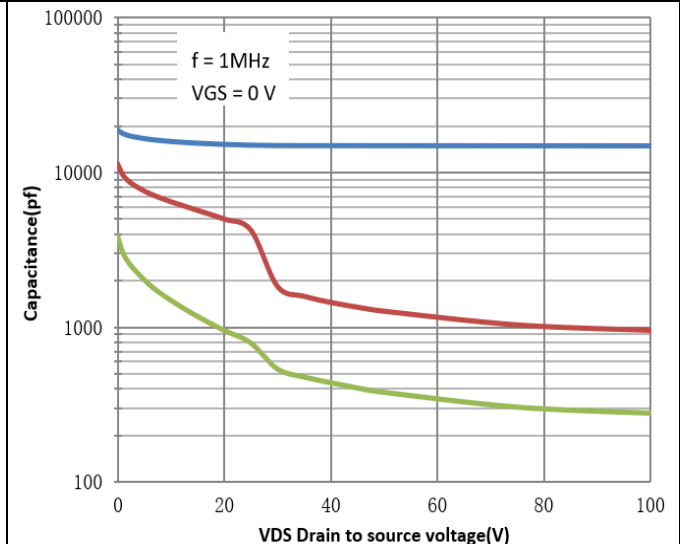
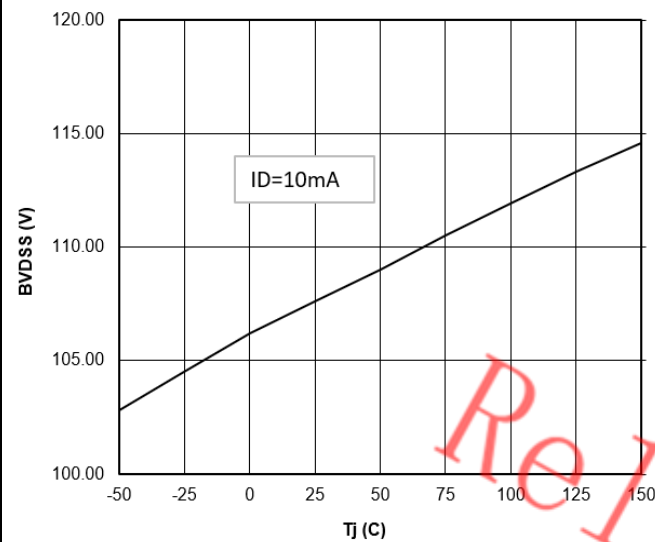
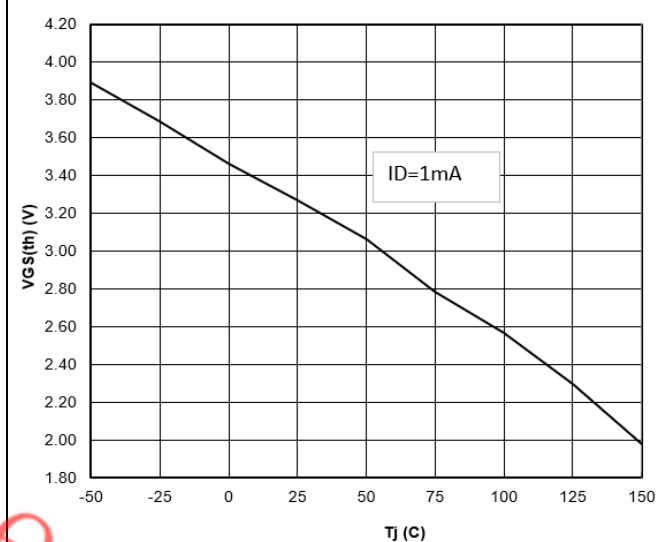

 $C = f(V_{DS}); V_{GS} = 0\text{V}; f = 1\text{MHz}$

Diagram 7: Typ. Drain-source breakdown voltage



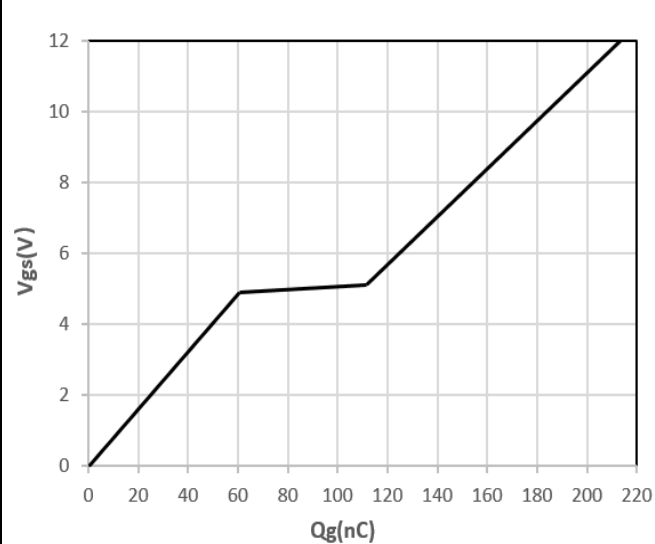
$$V_{BR(DSS)} = f(T_J); I_D = 10\text{mA}$$

Diagram 8: Typ. Threshold voltage



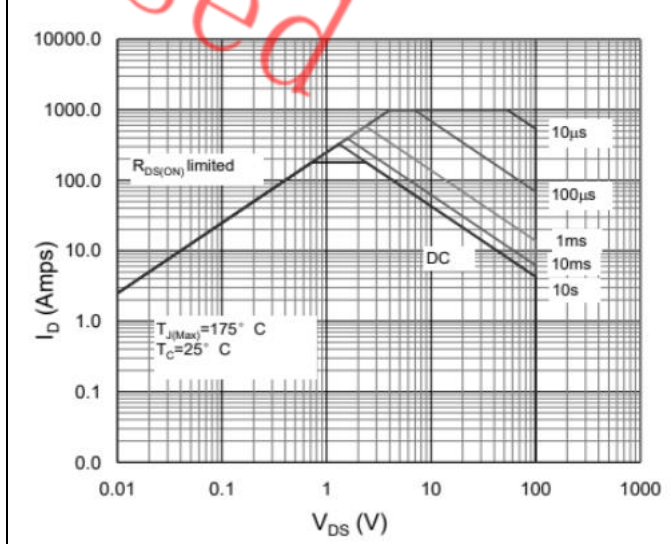
$$V_{th} = f(T_J)$$

Diagram 9: Typ. Gate charge



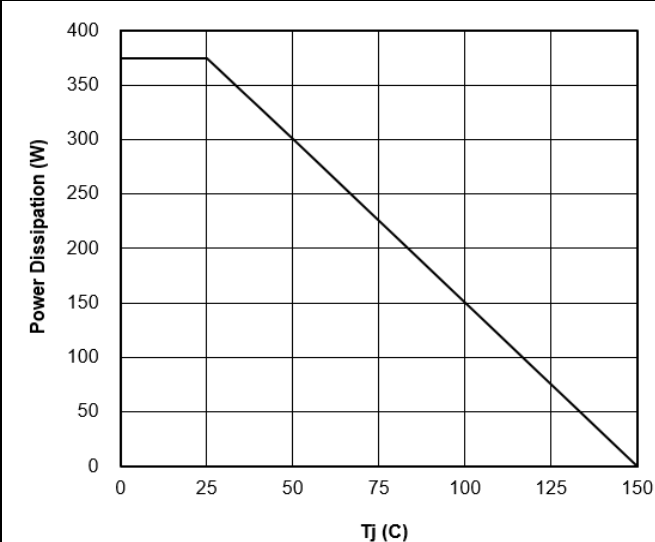
$$V_{GS} = f(Q_{gate}); I_D = 20\text{A pulsed}; \text{parameter: } V_{DD}$$

Diagram 10: Typ. Maximum Safe Operating Area



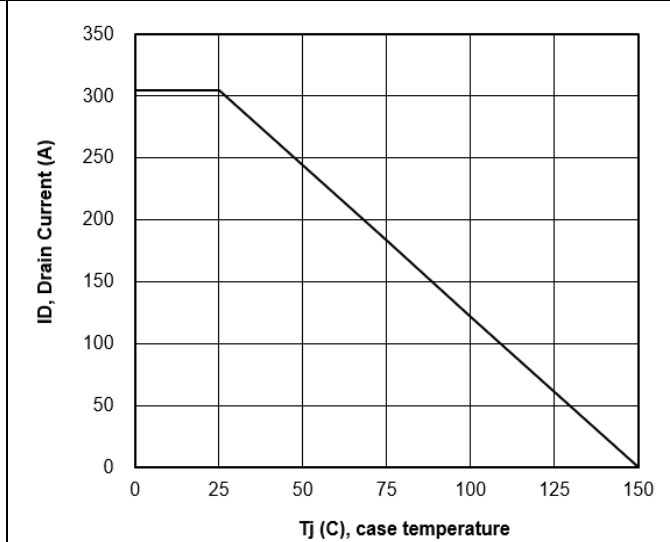
$$I_D = f(V_{DS}); T_C = 25^\circ\text{C}; D = 0; \text{parameter } t_p$$

Diagram 11: Typ. Power Dissipation



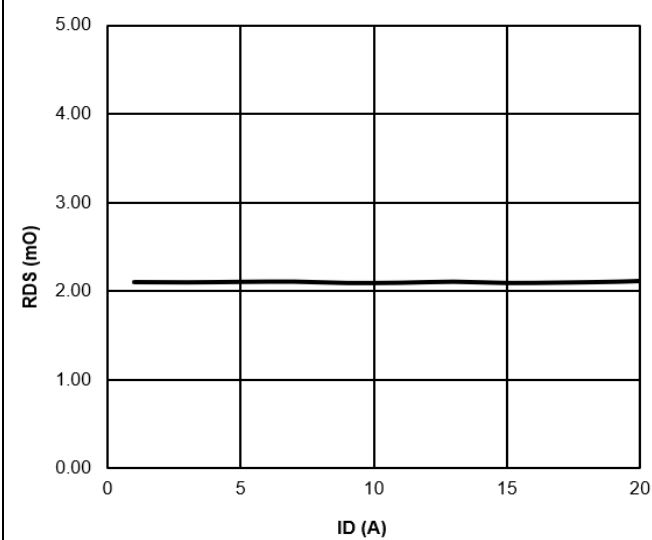
$$P_{100} = f(T_J);$$

Diagram 12: Typ. Drain Current De-rating



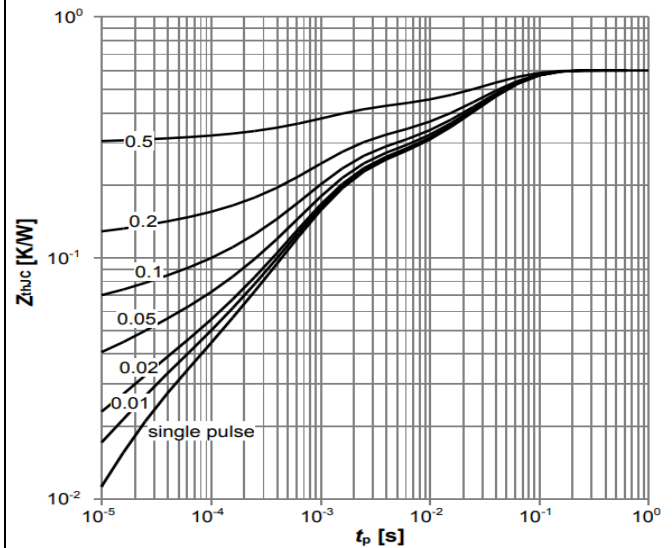
$$I_D = f(T_J);$$

Diagram 13: Typ. On-Resistance vs. ID (TO247)



$R_{DS(on)}=f(I_D)$; $T_J=25^{\circ}\text{C}$; parameter: $V_{GS}=10\text{V}$ (TO247)

Diagram 14: Typ. Max. transient thermal impedance



$Z_{thJC}=f(t_p)$; parameter: $D=t_p/T$

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5 Test Circuits

Table 8 Diode characteristics

Test circuit for diode characteristics	Diode recovery waveform
$R_{G1} = R_{G2}$	

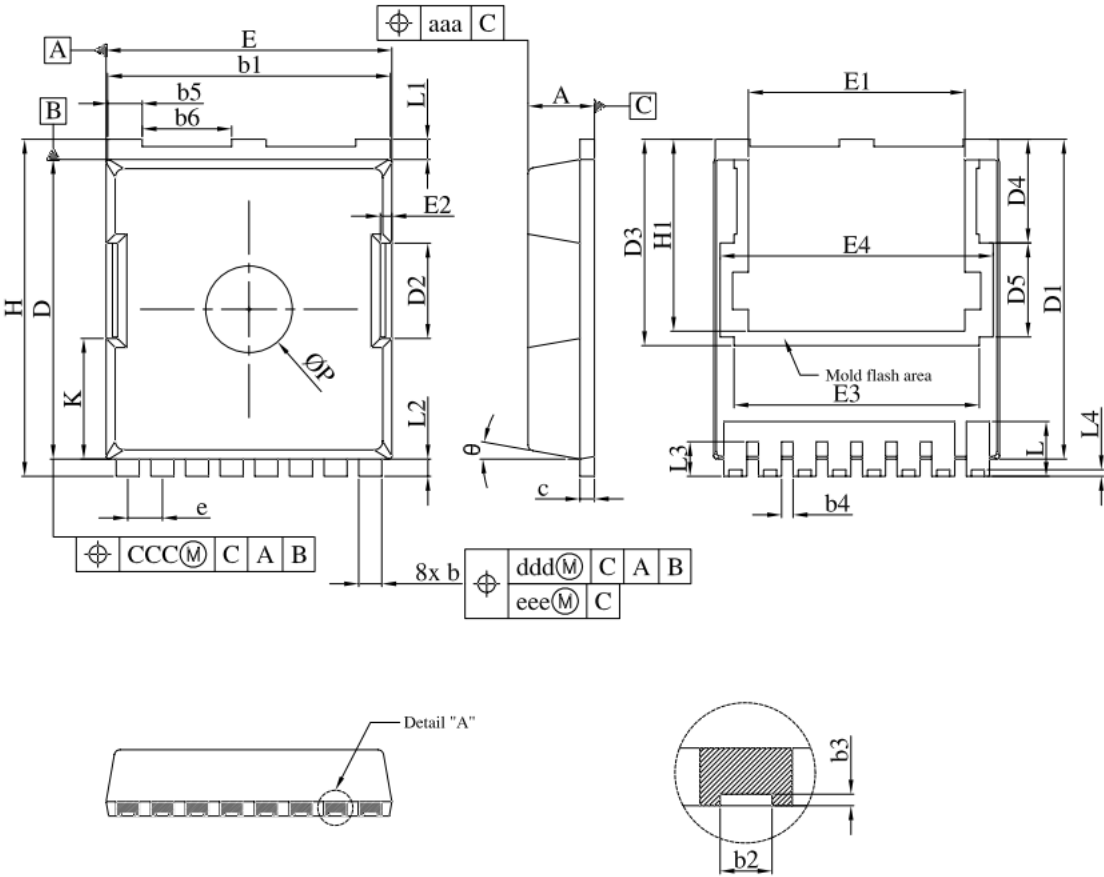
Table 9 Switching times

Switching times test circuit for inductive load	Switching times waveform
V_{GS} V_{DS}	

Table 10 Unclamped inductive load

Unclamped inductive load test circuit	Unclamped inductive waveform
I_D V_{DS}	

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SYMBOL	COMMON		
	MILLIMETER		
	MIN.	NOMINAL	MAX.
A	2.20	2.30	2.40
b	0.70	0.80	0.90
b1	9.70	9.80	9.90
b2	0.36	0.45	0.55
b3	0.05	0.100	/
b4	0.30	0.40	0.50
b5	1.10	1.20	1.30
b6	3.00	3.10	3.20
c	0.40	0.50	0.60
D	10.28	10.38	10.55
D1	10.98	11.08	11.18
D2	3.20	3.30	3.40
D3	7.15		
D4	3.59		
D5	3.26		
e	1.10	1.20	1.30
E	9.80	9.90	10.00
E1	7.40	7.50	7.60
E2	0.30	0.40	0.50
E3	8.50		
E4	9.46		
H	11.50	11.68	11.85
H1	6.55	6.65	6.75
K	4.08	4.18	4.28
L	1.60	1.90	2.10
L1	0.50	0.70	0.90
L2	0.50	0.60	0.70
L3	1.00	1.20	1.30
L4	0.13	0.23	0.33
P	2.85	3.00	3.15
θ	10° REF		
aaa	0.20		
ccc	0.20		
ddd	0.25		
eee	0.20		

Outline PG-TOLL(JQ)

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Revision History

Revision	Date	Subjects (major changes since last revision)
1.0	2023-12-11	Preliminary version

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